

02/22/02
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Docket No.: M-12589 US

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11017 U.S. PTO
10/080468



BOX PATENT APPLICATION
Commissioner for Patents
Washington, D.C. 20231

Enclosed herewith for filing is a patent application, as follows:

Inventor: Hua Ji
Title: HDP CVD Process For Void-Free Gap Fill Of A High Aspect Ratio Trench

- Return Receipt Postcard
 This Transmittal Letter (in duplicate)
 12 page(s) Specification (not including claims)
 4 page(s) Claims
 1 page Abstract
 6 Sheet(s) of Drawings
 2 page(s) Declaration For Patent Application and Power of Attorney
 1 page(s) Recordation Form Cover Sheet (in duplicate)
 1 page(s) Assignment

CLAIMS AS FILED

For	Number Filed	Number Extra	Rate	=	\$	Basic Fee
Total Claims	29	-20	x \$18.00	=	\$	162.00
Independent Claims	2	-3	x \$84.00	=	\$	0.00
<input type="checkbox"/> Fee of _____ for the first filing of one or more multiple dependent claims per application					\$	
<input type="checkbox"/> Fee for Request for Extension of Time					\$	

Please make the following charges to Deposit Account 19-2386:

- Total fee for filing the patent application in the amount of \$ 902.00
 The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to Deposit Account 19-2386.

EXPRESS MAIL LABEL NO:
EV 022456809 US

Respectfully submitted,

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